ADVANCED ASSEMBLY

TECHNOLOGY

DOU YEE ENTERPRISES

The premier total industrial solutions provider in the Asia Pacific region, serving with distinction in the semiconductor, data storage, electronics and biomedical industry since 1982.

We have 45 international branch offices strategically located around the World to give customers the fastest and most accessible products and services.

Our manufacturing plants, located in Singapore, Malaysia (Seremban), China (Suzhou), France and Poland are governed by consistent quality systems with ISO 9001:2015 and ISO 14001:2015 certifications.

You can rely on us for products and services that are comprehensive in range, reliable in quality, accessible in location, and backed up by our many years of experience and expertise.

Dou Yee, your preferred partner in the industrial world.

PAGE OF CONTENTS

Company	Products	Page
AMX AUTOMATRIX	X-Sinter P200 Series • X-Sinter P100 Series • X-Sinter P50 Series	04-05
CAPCON	AvantGo Series Die Bonder	06
saki	3D AXI 3Xi Series	07
GPD Global Precision Dispensing Systems	Peel Back Force Tester	08
ELITE ROBOTS	Collaborative Robots CS Series • Collaborative Robots EC Series	09
MYCRONIC	MYTower™ • MY700™ • MYPro I™ series 3D AOI • PI™ series 3D SPI	10-11
SMT THERMAL DISCOVERIES	SMT Vacuum Reflow Oven • SMT A-Series FORMIC ACID	12-13
YOUNGPOOL	M2-900 Laser Marking System • Auto Splicing System • Vacuum Degassing System (Inline/Offline) • Material Handling Systems	14-15
ETS GDK	High Speed Odd Form Component Insertion	16
finetech	Micro Assembly System • Advanced Rework System	17
pbt works	MiniSWASH • CompaCLEAN • HyperCLEAN • HyperSWASH	18-19
ZESTRON High Precision Cleaning	Cleaning Applications in the Electronics Assembly Process	20
Asec	Adhesive System Engineering Consulting	21
MUSASHI ENGINEERING,INC.	FAD 5100S-WH • FAD 2500 • Image MASTER™ 350pcSmart • XCROSS MASTER™ Sx series • Super EXM™ IV • ML-8000X • Super Jet™ MJET-S • AeroJet MJET-A • Measuring Master MPP-1 / MPP-3	22-27
HOYA	UV LED Type • UV Light Source Type • UV Meter • UV Light Technology • Adhesion/Bond Cure • Seal / Coat	28-29

Spray Coating, Dispensing

MUSASHI ENGINEERING,INC.

SMT PCBA Soluti

SMT PCBA Solutions

Immersion, WaveSolder

Odd Shape Component

Auto Insertion

A Company

SMD Tower Storage

MYCRONIC

DOU YEE ENTERPRISES

Collaborative Robots

Loader, Unloader

Conveyor Systems

YOUNGPOOL

Laser Marker,

Laser Board Cutting

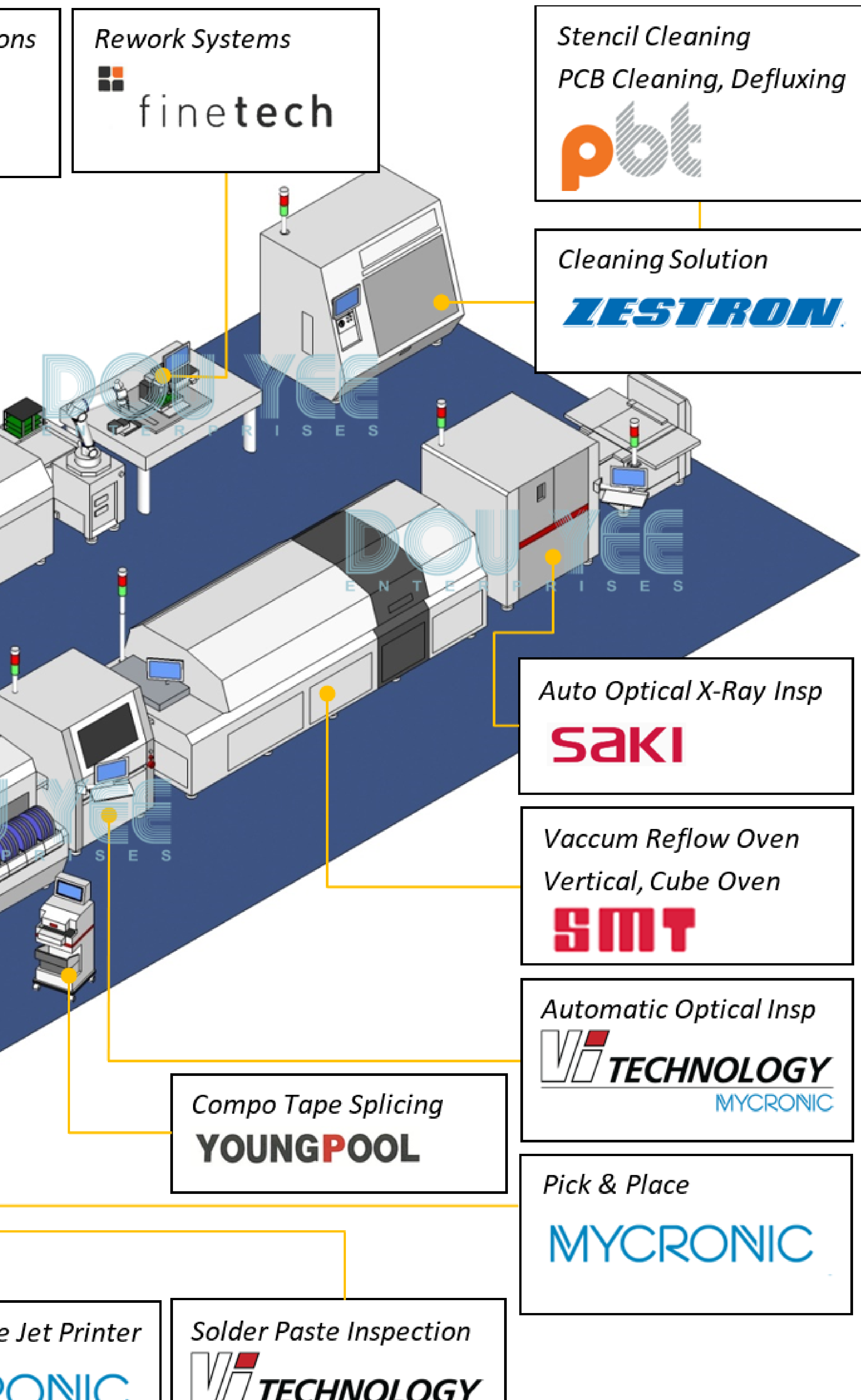
YOUNGPOOL

Stencil Printer

MYCRONIC

Solder Past

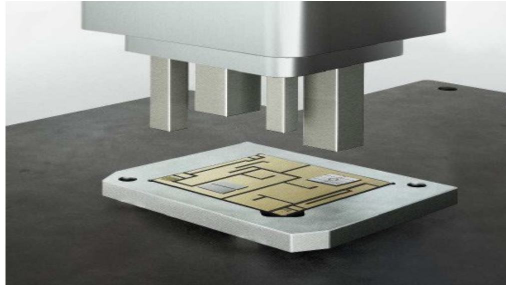
MYCR



OUR PARTNERS

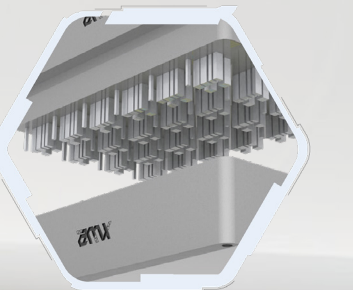
- SMT THERMAL DISCOVERIES
- Vi TECHNOLOGY
- finetech
- MYCRONIC When passion meets innovation
- MUSASHI ENGINEERING,INC.
- pbt works
- ZESTRON High Precision Cleaning
- GDK
- ETS
- ELITE ROBOTS
- YOUNGPOOL
- saki

X-Sinter P200 Series

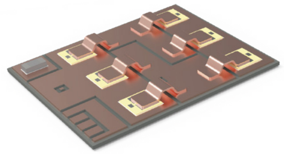


Patented State-of-the-art Fully Automatic Sintering Press

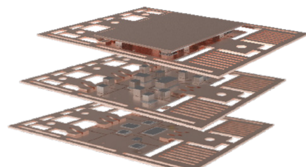
- Full Inline unit
- MicroPunch system [AMX Patented]
- Large Sintering area 350mm x 270mm
- High Sintering Force up to 980 KN
- Oil Free
- Full inert atmosphere cabinet (N2 or other gases)
- Built-in O2 analyser, maintained less than 100ppm
- Load Cell force measurement for Quality control
- Smallest footprint W1400 x D1600 x H1600 mm
- Automatic protective film feeding
- AMX Vision system



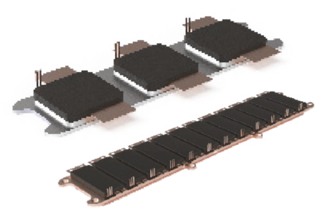
Die & Clip Sintering

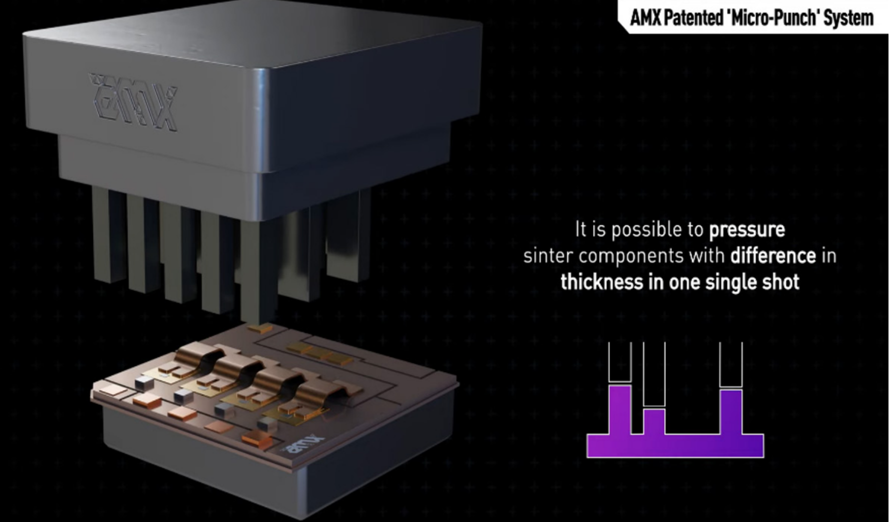


DSC (Double Side Cooling)



Package Sintering





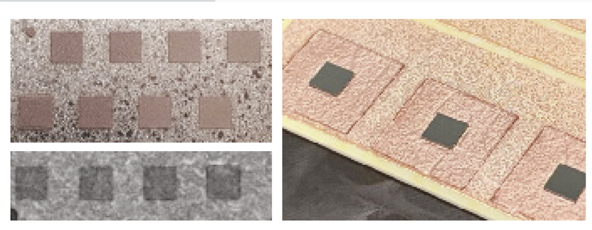
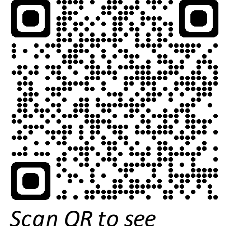


Figure 8b Copper Paste

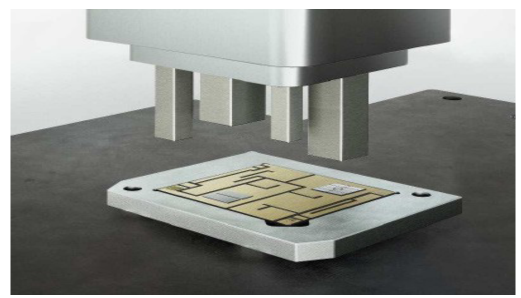
All AMX equipment are ready for Cu pressure sintering

Source: AMX Automatrix



Scan QR to see MicroPunch in Action

X-Sinter P100 Series



Patented Micro-Punch Semi Automatic Sintering Press

- Micro-Punch press tool to reach every single component on the substrate
- Sinter Multiple Dies with different die thicknesses
- Max. pressing area: 160mm x 160mm
- Max. temperature: 350°C
- Max. clamping force: 160kN
- Max. Sintering Pressure: 40MPa
- Controlled Atmosphere: N2, Vacuum, Forming Gas
- High Precision, Flexible, Accurate Process Control
- Suitable for R&D, Small, Medium batch Production

P100 Series

AMX

X-Sinter P50 Series

Manual / Semi Automatic Sintering Press

- Sinter Dies with different die thicknesses
- Sinter Wafer and Lamination with P54, P55
- Max. Press area: 75x75mm (P51) – 300x300mm (P55)
- Max. temperature: 350°C
- Max. Preheat temperature: 250°C
- Max. clamping force: 16kN (P51) – 300kN (P55)
- Max. Sintering Pressure: 40MPa
- Controlled Atmosphere: N2, Vacuum, Forming Gas
- High Precision & Flexibility with Many Options
- Suitable for R&D, Prototyping, Quality Inspections

Semi Auto P54,P55

Manual P51,P52,P53

AvantGo Series Die Bonder

Innovative solutions for :

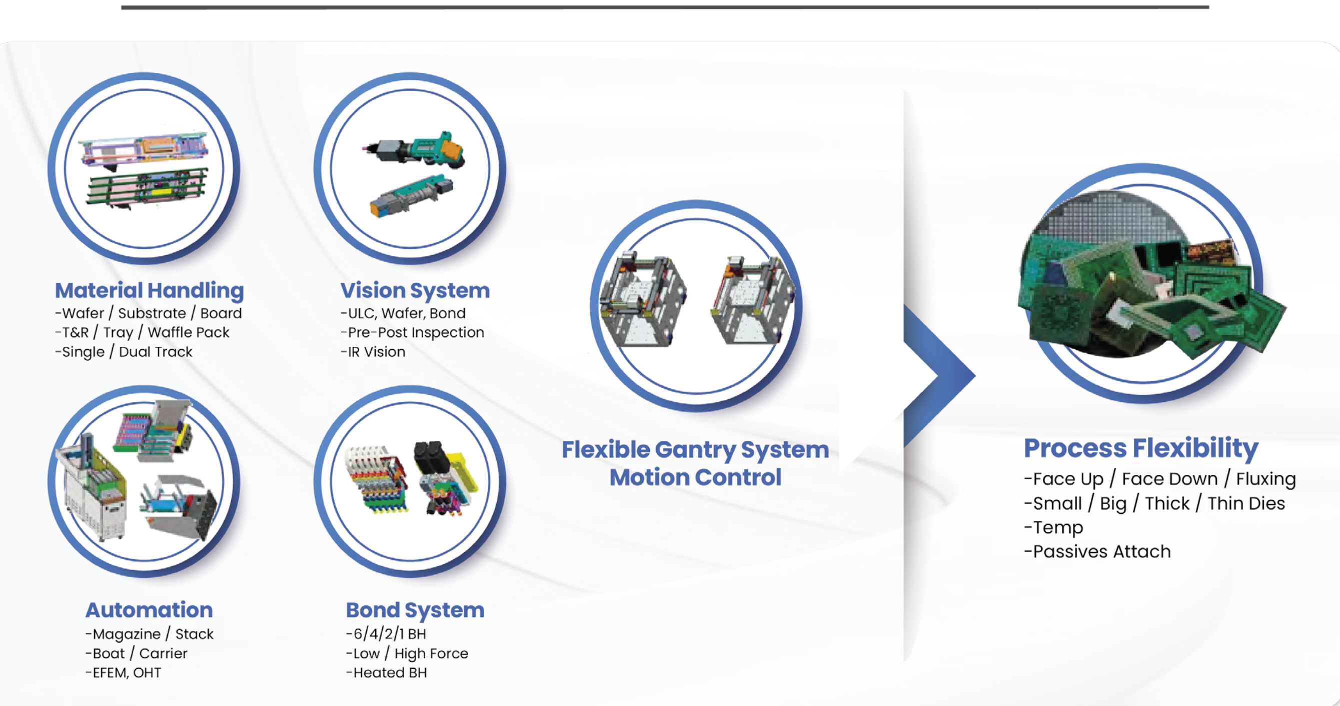
- Flip-Chip,
- Chip-on-Wafer,
- Package-on-Package,
- Stack Die,
- Panel-Level Die,
- Multi-Chip Die

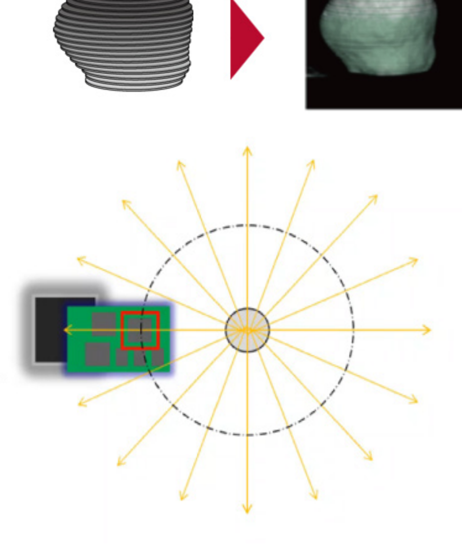
Main Features :

- Small Footprint
- Input Options: Wafer, Jedec Tray, 2" Waffle Pak Feeder, Tape Feeder
- UPH up to 11K Process Dependent
- Placement Accuracy +/- 5um to +/- 2um configuration
- Process: Face Up, Face Down capable within a machine
- 2 x Gantry, up to 12 Bond Heads
- 2 x Wafer Loaders
- Bond Area up to 750x700mm capable

CAPCON Die Bonder is designed for Advanced Assembly & Packaging Semiconductor backend

Modular Building Blocks to Meet Process Requirement





3D AXI 3Xi Series

Printed circuit board

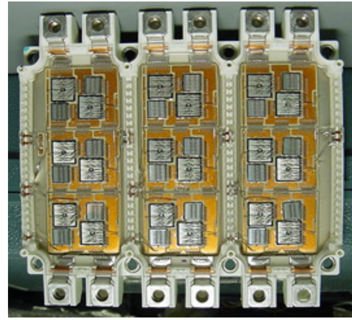
- Solder ball joint inspection of BGAs
- Solder joint inspection on the back face of QFNs
- Solder joint inspection for all parts such as chip, connector, insert parts on PCBs

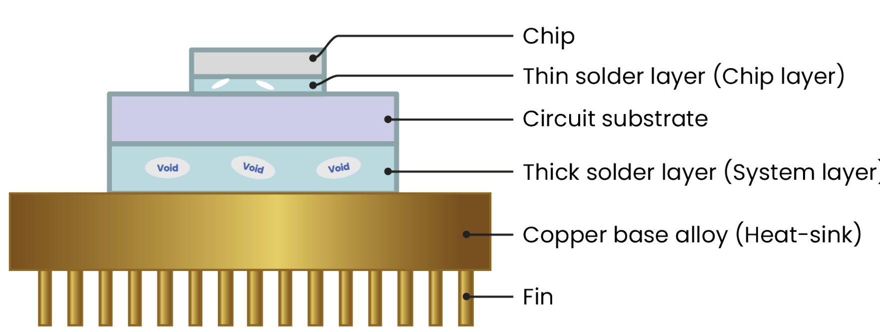
Semiconductor

- High-resolution inspection
- Void inspection of Laser Through-hole (LTH)
- Flip-chip bonding inspection
- Package-on-Package (PoP) soldering inspection

Power module

- High power X-ray tube (180kV)
- Void inspection inside solder joint of Insulated Gate Bipolar Transistor (IGBT) module





Peel Back Force Tester

GPD's Peel Back Force Tester with FORCEWare™ software is being used to set peel back standards for the entire industry.

Control • Information • More Efficent Production

Test Graph

When a peel back force test begins, its progress displays on the test graph. Upon test completion, specific and summary data are displayed in a Test Results window. Many different graph forms can then be generated.

Current Results Chart

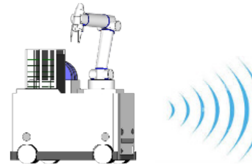
Displays complete results of test. Results can be saved and reviewed.

Specifications

Force Measuring Range	0 – 250 grams
Speed	100 - 600 ± 5 mm/minute in 50 mm increments
Angle	160 - 180 degrees
Accuracy	± 1%
Tape Width	8, 12, 16, 24, 32, 44, & 56 (optional 8 t o 120 mm)
Dimensions	318 H x 737 W x 368mm x 30 kg
AC Input	100 - 240 VAC
PC/Laptop Control	Windows based proprietary FORCEWare™ Software, Data capture, SPC Analysis

Collaborative Robots

CS Series



GPD GLOBAL

ELITE ROBOTS

Top-of-the-line Solution for Advanced Automation

- Up to 1800mm (1.8m) Radius Working Area!
- ISO 10218-1 and 13849-1, PLd Cat 3... Safety Standards
- Over 20 configurable Safety Functions
- Over 80 adjustable levels of Collision Detection
- Rich Interconnectivity (IO, RS485,TCP/IP,Modbus,Ethernet...)
- IP65 Protection Standard (Upgradable to IP68)
- 12.1" Full Touchscreen Teaching Pendant
- Intuitive, Easy to Understand, Customizable GUI (Python)

	CS63	CS66	CS68	CS612	CS616	CS618	CS620	CS625
PAYLOAD	3 kg	6 kg	8 kg	12 kg	16 kg	18 kg	20 kg	25 kg
RADIUS	624 mm	914 mm	820 mm	1304 mm	1100 mm	954 mm	1800 mm	1500 mm
ACCURACY	± 0.02 mm	± 0.03 mm	± 0.03 mm	± 0.05 mm	± 0.05 mm	± 0.05 mm	± 0.1 mm	± 0.08 mm
MAX TCP SPEED	2.0 m/s	2.8 m/s	2.8 m/s	3.4 m/s	3.4 m/s	3.4 m/s	3.9 m/s	3.3 m/s
TOOL I/O	12v/24v 3A,2A,1A	12v/24v 3A,2A,1A	12v/24v 3A,2A,1A	12v/24v 3A,2A,1A	12v/24v 3A,2A,1A	12v/24v 3A,2A,1A	**T1:** 12v/24v 3A,2A,1A **T2:** 24V, 5A	**T1:** 12v/24v 3A,2A,1A **T2:** 24V, 5A

EC Series

Excellent Price-Performance, Superb Utility, Flexible Mounting Capabilities

	EC63	EC66	EC68-08	EC616	EC612	EC64-19
PAYLOAD	3 kg	6 kg	8 kg	16 kg	12 kg	4 kg
RADIUS	624 mm	914 mm	820 mm	954 mm	1304 mm	1900 mm
ACCURACY	± 0.02 mm	± 0.03 mm	± 0.03 mm	± 0.03 mm	± 0.05 mm	± 0.1 mm
MAX TCP SPEED	2.0 m/s	2.8 m/s	2.5 m/s	2.8 m/s	3.2 m/s	4.0 m/s

MYTower™

Automated Intelligent Material Storage & Handling

- Fast storage & retrieval of components
- Minimize material movements, maximize assembly line utilization
- Reduce manual labor & retrieval times
- Minimize floorspace, maximize capacity
- Flexible placement within production
- Easy integration with any system
- Controlled environment and floor life monitoring for MSD components
- Alarms for material availability
- Traceability functions
- Quantity control
- ERP & MES connectivity
- MYTower 7+: 1,148 reels (max)
- MYTower 6x: 2,468 reels (max)

MYTower Storage

- 4", 7", 13" and 15" reels
- 4 - 56 mm reel widths
- JEDEC trays in tray boxes
- Smart Box
- Pallets for reels on Agilis feeder

MY700™

Hi-Speed Jet Printing For complex high mix, high-volume or prototyping production environments.

- Very fast and accurate dispensing
- Fast changeovers
- Software driven – no stencils, no cleaning
- Jet frequency : Up to 1,080, 000 dph
- MY700JX – Dual Head (Solder Paste and adhesive jetting)
- MY700JP – Solder Paste jetting
  - Dot vol: 2-35 nl
  - Dot dia: 0.21 mm
- MY700JD - SMA, adhesives, UV materials and epoxies jetting
  - Dot vol: 5-1000 nl
  - Dot dia: 0.2 mm

MYPro I™ series 3D AOI

Faster and sharper processing

- AI-assisted inspection software
- Next generation 3D vision technology
- Resolution: 3.45um (with sub-pixel)
- Inspectable package size (min): 008004 (0201 metric)
- Inspect SMT, THT, Press-fit, Automated Optical Metrology (AOM)
- High flexibilty for high mix, heavyweight board
- High performance for high productivity

IRIS

2D + 3D Inspection - Faster. Sharper. Smarter.

- Accelerating electronics inspection
- Speed and resolution with zero compromises
- Smarter computing

Sharper 3D imaging

PI™ series 3D SPI

Accurate solder paste inspection

- Perfect solder joints made simple
- Highly accurate SPI data - warp compensation with accurate Z referencing technology
- Effortless with smart auto-programming functions - ensure high-quality inspection regardless of operator experience
- Superior repeatability - Multi-frequency, multi-pattern Moiré and patented dual Z-axis motion.
- Real time process monitoring and Improvement with MYPro Analyze.

MyPro Analyze

- Improves and maximizes first-pass yield

MYCRONIC

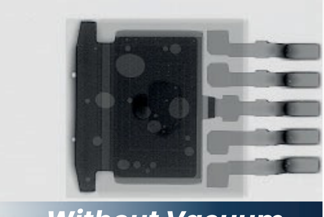
SMT VACUUM REFLOW OVEN

Pre-Heating zones | Peak zones | Vacuum | Cooling zones

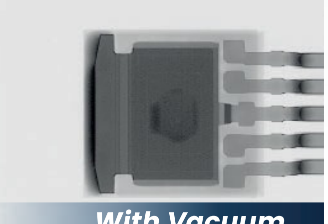
Vacuum Chamber

- **Voids will be reduced up to 99%**
- Made of stainless steel
- Sturdy towards thermal and physical stress
- Only one sealing in the vacuum chamber
- Easy, fast maintenance / exchange
- Easy accessibility due to the mounting point of the hood
- **Available in two sizes: 320 mm length or 450 mm length**
- **Process Temperature (Pre-heat/Peak/VAC) :**

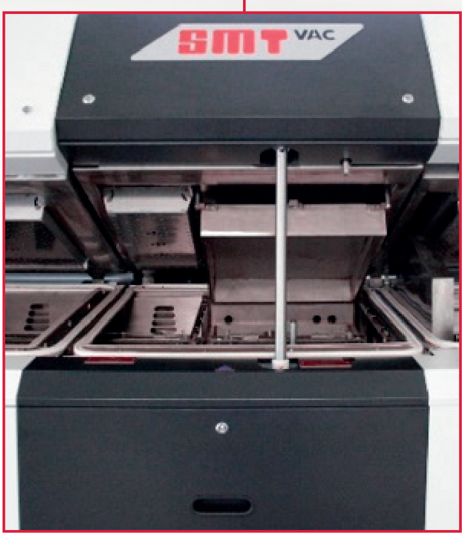
Max. 300oC/ 350oC/ 300oC



Without Vacuum



With Vacuum



Key Features

» Constant process gas flow, adjustable via frequency converter

» Encapsulated, maintenance-free fan motor, no leak

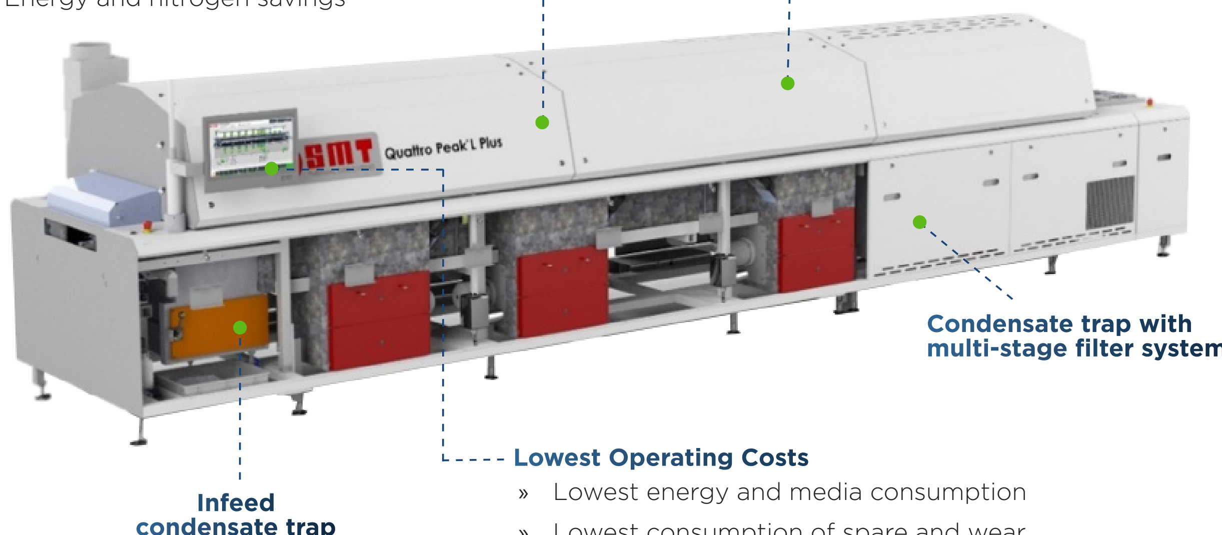
» Energy and nitrogen savings

Precise Nitrogen Control

» Integrated lambda sensor technology and real-time continuous measurements of residual oxygen

» Less nitrogen consumption

» Easy calibration (exchange can be done)



Condensate trap with multi-stage filter system

Infeed condensate trap

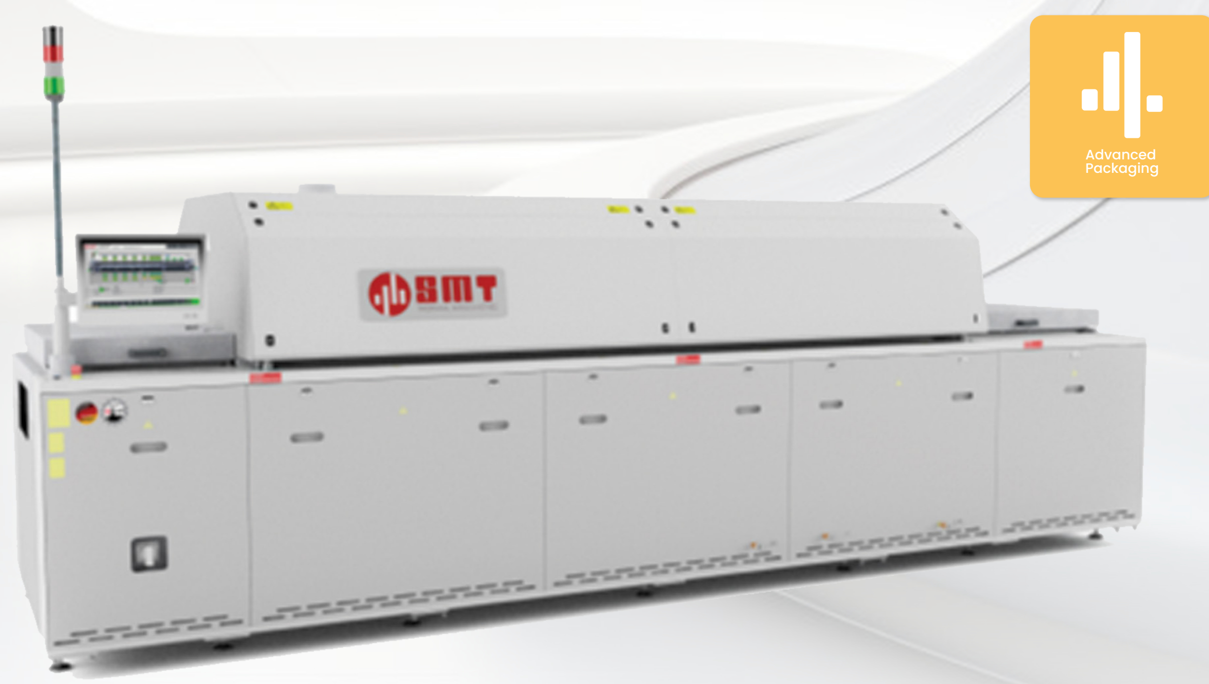
Lowest Operating Costs

» Lowest energy and media consumption

» Lowest consumption of spare and wear parts (e.g. rails, chain, fan motors...)

SMT A-Series FORMIC ACID

A Soldering System for Semiconductor Production & Advance Packaging with Formic Acid Application & High Temperature Setting Option



System covers a variety of set up scenarios:

Atmosphere

- Formic Acid* (CH202)
- Hydrogen* (H2-100%)
- Nitrogen (N2-requirement)

Temperature

- High temperature solder up to 450 ° C*
- SAC 305*
- Tin-antimony alloy*

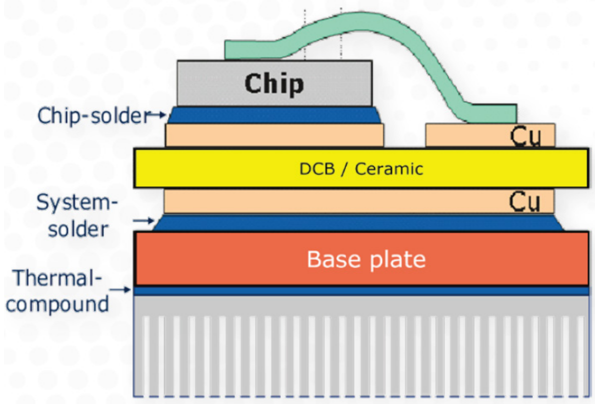
Process

- Vacuum
- Preforms with Flux*
- Preforms without Flux*

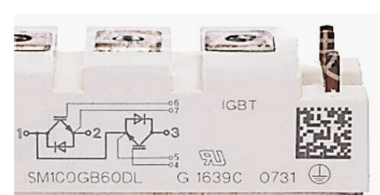
****Cannot combined in one category***

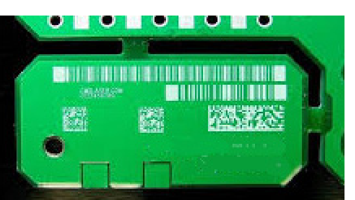
Possible Application

- IGBT
- DBC
- Die Attached
- Opto Laser
- Heatsink
- General Copper Surface
- Vapour phase substitution
- Cleaning process



M2-900 Laser Marking System

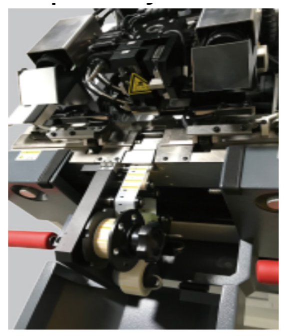


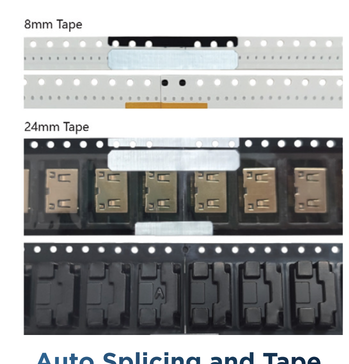


- 1D, 2D barcodes, text, logos, optical characters
- 4 types of Laser – CO2, UV, Green, Fiber
- Top and Bottom and Dual-head Configuration, Dual-Lane
- Std Dual-Camera Configuration, Simultaneous Reading and Writing
- Fume Detection
- Optional Z-Axis for marking different Heights

Auto Splicing System

L-900 L-4

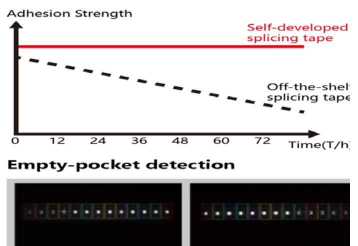




Proprietary Bond Head **Auto Splicing and Tape**

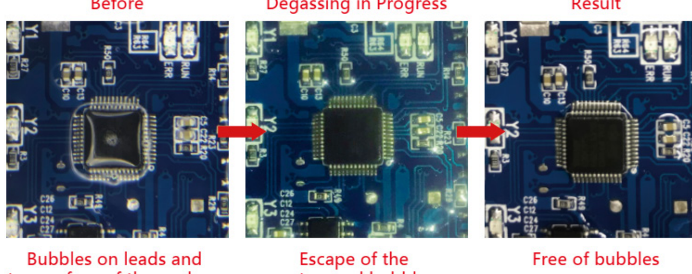
- Support 8mm (L-4), 8-32mm (L-900) Component Tape Width
- Support component Tape thickness 0.25-1.25mm
- Support deep pocket up to 4.1mm (L-4) / 9.0mm (L-900)
- Excellent Splicing FPY up to 98%
- Standard with intelligent Vision System
- Standard LCR verification for Capacitors, Resistors
- Auto adjustment for LCR probe from component size 01005
- Auto empty pocket detection and pitch verification
- Continuous operation for up to 16hrs
- » MES integration via WiFi or Network port

Adhesion Stength and Durability



Vacuum Degassing System (Inline/Offline)

- Degassing after Potting, Coating, Adhesive Dispensing
- Inline Configuration for integration to Production line
- Single lane single chamber
- Degassing using Vacuum and Heat
- Adjustable Vacuum Profile
- Std Maximum PCB Size 450mm x 450mm
- Easy Operation



Material Handling Systems

YP-1B101
Magazine Loader

YP-1B100XL
Inspection conveyor

YP-1B100
Auto width conveyor

YP-3A150
Telescopic door conveyor

- Magazing Loader
- PCB Stacker
- Flipper Conveyor
- Transverser
- Telescopic Track
- Single / Dual Lane Conveyor

- Inspection Conveyor
- Cooling Conveyor
- Buffer Conveyor
- Buffer Machine
- NG-OK Magazine Unloader

YP-2YA050XL
Single lane inspection conveyor

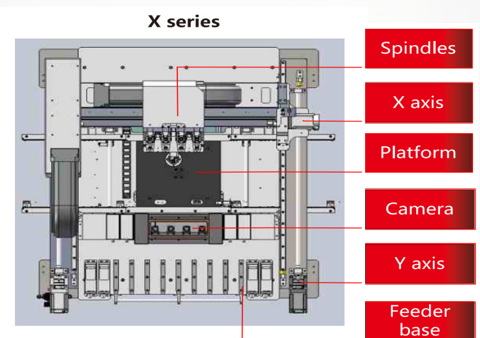
YP-1T100
NG buffer conveyor

YP-1N100
NG-OK Magazine Unloader

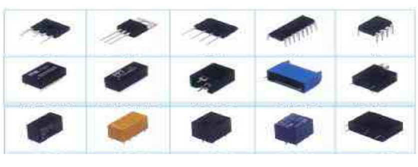
YP-4A050
Stacker Loader

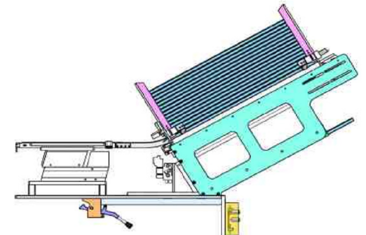
High Speed Odd Form Component Insertion

- High Speed Component Insertion 0.5s per component
- High Insertion Accuracy 0.03mm
- Component Size up to W 40mm x H 30mm
- Variable Insertion Direction 0-360deg
- Up to 16 feeders (Front and Back)
- Up to 8 Spindle/Pick-up Heads
- Automatic Pick-up Exchanger
- Pin Detection and Camera Checking before placement
- Variable Feeder Types – Tape, Tube, Tray, Bowl
- Casted Frame Structure – Minimized Vibration

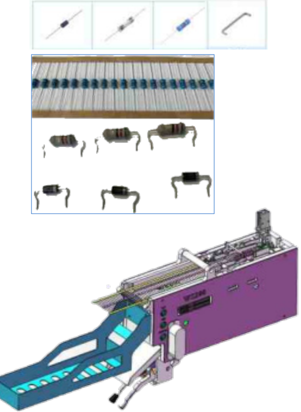


Tube Feeder

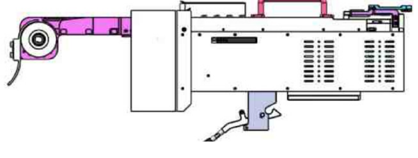




Axial Feeder

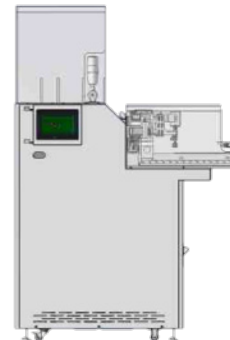


Radial Feeder



Bowl Feeder

Tray Feeder



Micro Assembly System

FINEPLACER FEMTO 2

Flexible Assembly Platform

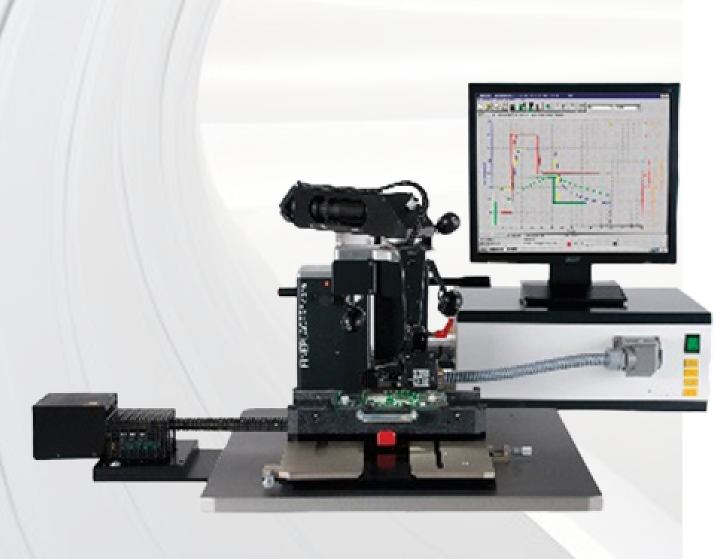
- Placement accuracy 0.5um @ 3 sigma
- Component sizes from 0.05x0.05mm to 100x100mm
- Fully automated operation
- Pattern recognition for automated placement and bonding processes
- FPXvison™ maximum resolution across large field of view

FINEPLACER PICO 2

Flexible Assembly Platform

- Placement accuracy 3µm
- Component sizes from 0.05x0.05mm to 100x100mm
- Supported substrate size up to 350x300mm2
- Bonding forces up to 500N
- Heating Temperature from 40°C to 450°C

Advanced Rework System



FINEPLACER CORE

Industry leading cost-effective rework

- Placement Accuracy of 25um
- Component sizes from 0.25x0.25mm up to 90x90mm
- Board size up to 400x310mm
- Automated processes with force measurement
- Vision alignment system with Fixed beam splitter
- Real time process observation camera

MiniSWASH

Automatic Spray Cleaning System

Advantages of Mini SWASH

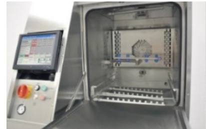
- Fully automatic spray-in-air closed loop zero drain system
- Low consumption of chemicals and water
- Synchronous, double-sided, constant speed motor-driven nozzle manifold
- **Rotary Direct Spray Bars**
- Hot air direct dry technology
- Synchronous motion check
- Anti-collision system

CompaCLEAN

Automatic Spray Cleaning System

Advantages of COMPACLEAN

- Fully automatic spray-in-air closed loop zero drain system
- Illuminated glass door chamber for visual process control
- Intuitive touchscreen interface with Window OS
- Complete datalogging, Lan connectivity and optional barcode traceability
- Personalised password security
- **Oscillating Basket Fixed Spray Bars**
- High volume batch size
- Fixed nozzle system
- Powerful hot air dyer



HyperCLEAN

Automatic Spray Cleaning System

Advantages of HyperCLEAN system

- Single Basket or Double Basket
- Large chamber for high capacity
- Quick & Easy Loading with Pushcart
- Rapid Wash and Rinse
- Basket Oscillation (Short version only)
- Fast Drying

HyperSWASH

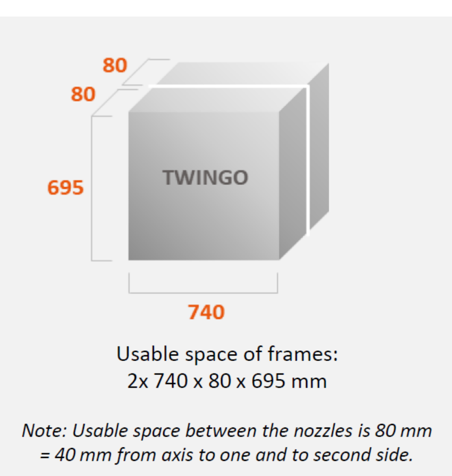
Automatic Spray Cleaning System

Advantages of HyperSWASH

- High Performance cleaning machine for water-based chemicals
- Double capacity configuration TWINGO
- High Performance direct spray technology
- 5 Stages process: Wash/Pre-Rinse/1.Rinse/2.Rinse/Dry
- Rapid Direct drying by heated air knife
- Illuminated glass door for visual processes control
- Intuitive touchscreen interface with Window OS
- 2 in 1 – Combo/Twingo

PBT

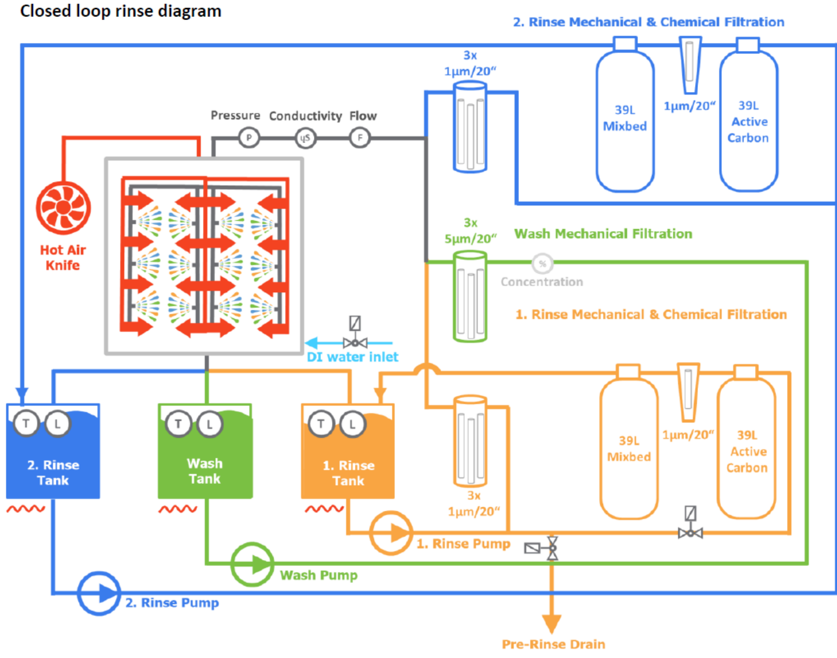
Usable Space of Chamber (Including fixtures & Clamping)



Usable space of frames:
2x 740 x 80 x 695 mm

Note: Usable space between the nozzles is 80 mm = 40 mm from axis to one and to second side.

Closed loop rinse diagram



Cleaning Applications in the Electronics Assembly Process

Solder Paste Printing
Inspection
Assembling
Reflow-Soldering
Cleaning

ZESTRON® EYE Mobile

ZESTRON® EYE

Dispensing
Assembling
Inspection
Wave Soldering
Cleaning

ZESTRON®
Bath Analyzer 10
Bath Analyzer 20

No.	Description	Products
1	Stencil	Vigon SC200 Vigon SC210
2	Mis-Print PCB	Vigon SC200 Vigon SC210
3	Pallets	Atron SP200 Atron SP300
4	Reflow Oven Condenser Trap	Atron SP200 Atron SP300
5	Reflow Oven Maintenance	Vigon RC101 Vigon RC303
6	Defluxing	Vigon A200 Vigon A201 Vigon N600 Zestron FA+ Hydron SE230A

ALL ZESTRON®,VIGON® and ATRON® based products fully comply with the requirements of the European Directives WEEE and RoHS

The Recommended Product for Cleaning in Electronics

Adhesive System Engineering Consulting

UV Curable | Heat Curable | Anaerobic

2. Underfill for Flip Chip

1. Underfill for BGA,CSP

3. Non Conductive Paste

7. COB Glob Top

4. Dam & Fill

6.Edge Bond/Corner fill

5. Low Temp Heat Curable

No.	Products	Characteristic
1	Underfill for BGA,CSP	Low CTE type / Low viscosity type
2	Underfill for Flip Chip	Capirally flow type / for Cu pillar / for TSV
3	Non Conductive Paste	Voidless NCP
4	Dam & Fill	Low stress type
5	Low Temp Heat Curable	80 X 10 mins
6	Edge Bond/Corner fill	High Viscosity & High thixotropy
7	COB Glob Top	High Tg type / Low stress type

ZESTRON

ASEC

FAD 5100S-WH

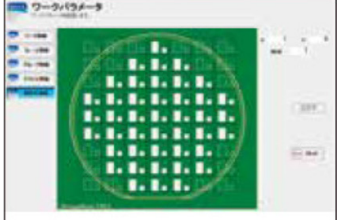
Back-end processes

For high throughput and high-quality dispensing

- High-speed dispensing with uninterrupted, continuous operation
- Automatically controls dispensing quantity
- Forms “leaf line” dispensing patterns that are ideal for avoiding voids
- Prevents large numbers of defects from occurring

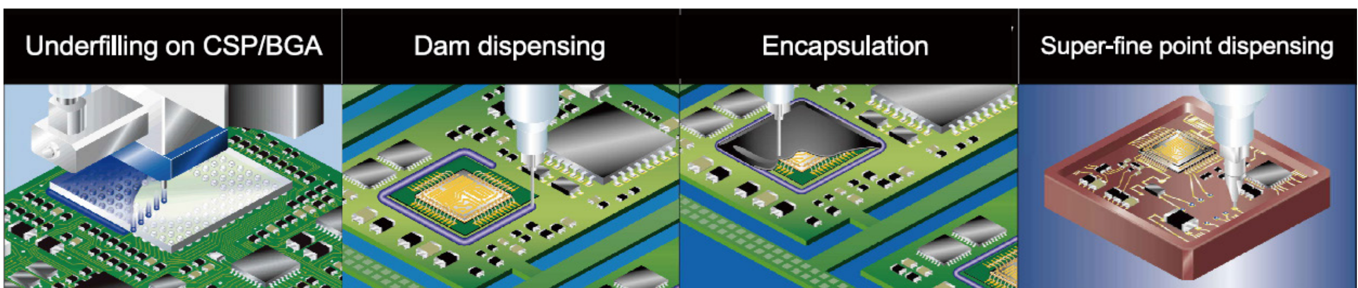
Applications

Underfilling CoW



Equipped with wafer mapping function!

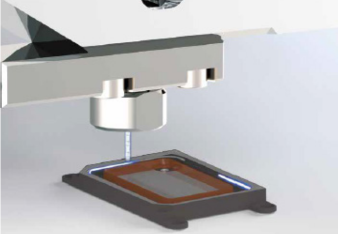
Configure any device layout on wafers.
Helps to reduce programming time significantly.

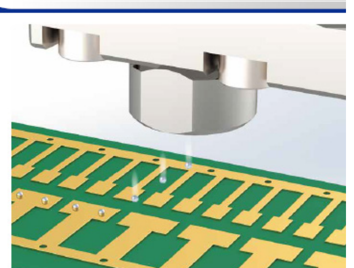


FAD 2500

Fully automatic dispensing mainframe

Application


Vibrating membrane attach on speaker

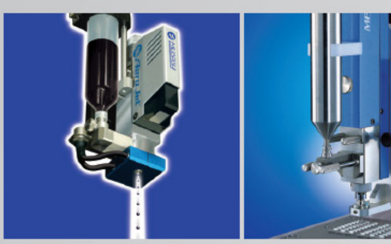

Ag dispensing on semiconductor lead frame

Multi-head compatibility Highly versatile to suit various applications

- High-speed dispensing with uninterrupted, continuous operation: Express JET function
- Automatically controls dispensing quantity: DVM function
- Forms “leaf line” dispensing patterns
- that are ideal for avoiding voids: MCD function (PAT.P)
- Wide range of standardized optional accessories.

MUSASHI

Dispenser Lineup


AeroJet®

MPP-1

SCREW MASTER®2

SuperΣCMII

IMAGE MASTER™ 350PC Smart

SMΩX series

No alignment

Complete correction of device position deviation

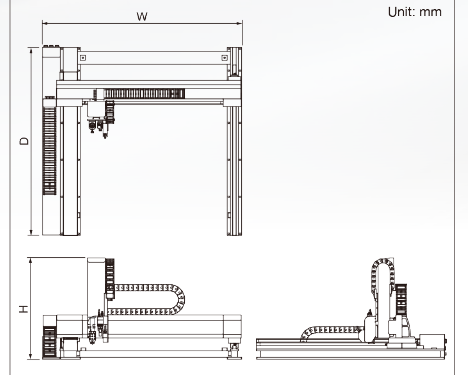
Dispensing shape

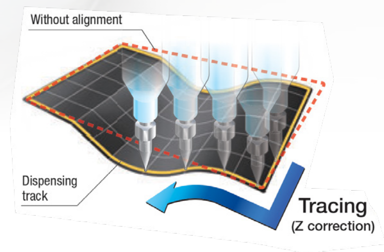
Tracing (Z correction)

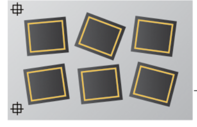
Complete 3-D Alignment

Automatic correction for individual differences in works and pallet array errors

Name		350PC Smart SM200ΩX	350PC Smart SM300ΩX	350PC Smart SM400ΩX	350PC Smart SM500ΩX
Model		350PCS-SM200 OMEGAX	350PCS-SM300 OMEGAX	350PCS-SM400 OMEGAX	350PCS-SM500 OMEGAX
Number of Controlled Axes		3 axes			
Control Method		PTP control/interpolation control			
Travel Range	X*Y	200 x 200 mm	300 x 300 mm	400 x 400 mm	500 x 500 mm
	Z	80 mm			
PTP Operation Speed Setting Range	X*Y	1 ~ 500 mm/s			
	Z	1 ~ 400 mm/s			
Interpolation Operation Speed Setting Range	X*Y	0.1 ~ 500 mm/s			
	Z	0.1 ~ 400 mm/s			
Repetitive Positioning Accuracy X*Y*Z		±0.005 mm			
Transportable Weight		20 kg			







Complete correction of device position deviation

MUSASHI

Name		350PC Smart XMΩX			
Model		350PCS-XM OMEGAX			
Number Of Controlled Axes		3 axes			
Control Method		PTP control/interpolation control			
Working Area X*Y		300x300 mm	400x400 mm	500x600 mm	700x800 mm
Working Area Z		150 mm			
PTP Operation Speed Setting Range	X*Y	1 to 500 mm/s			
	Z	1 to 400 mm/s			
Interpolation operation speed setting range	X*Y	0.1 to 500 mm/s			
	Z	0.1 to 400 mm/s			
Repetitive positioning accuracy X*Y*Z		±0.005 mm			
Tool Payload Weight		8.7 kg			
Main Unit Dimensions (excluding protrusions)	Width (W)	831 mm	931 mm	1031 mm	1239 mm
	Depth (D)	671 mm	771 mm	971 mm	1171 mm
	Height (H)	630 mm			
Main unit weight		80 kg	91 kg	120 kg	143 kg

Super ΣCM IV™

- **SIGMA Functions**

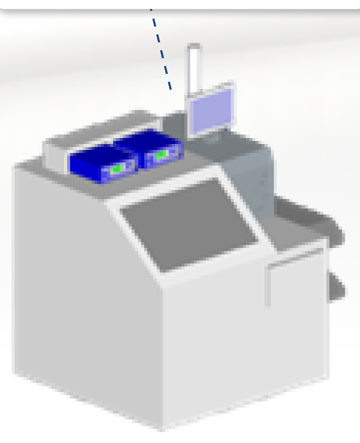
1. Automatic Volume Compensation
2. Automatic Vacuum Correction
3. Automatic Low Liquid Level Alarm

- **Full production control features**

1. Operation Log
2. Ethernet/LAN Port
3. PC communication via USB

- **Compact Design w/ Ener Saving mode**
- **Touch Panel Settings and Display**

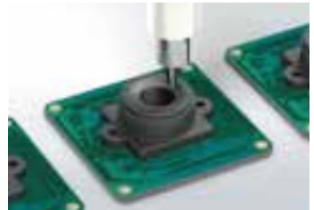
Die-Attach Paste Controller Replacement / Integration



Applications

Ag paste dispensing for die bonding

Solder paste dispensing to lead frame


UV dispensing for fixing the automotive camera lens

ML-8000X

- Fully Customizable Pressure/Time Increment
- Vacuum pressure auto control
- Various production control functions
- Operation log, self-diagnosis, emergency stop
- Improved operability with a 4.3inch touch panel
- Communication with PC with USB ports
- Network connection via LAN and Ethernet
- High-Res dispensing pressure setting option

ML-6000X

- Updated Model supersedes ML-5000XII
- Superior dispensing control accuracy
- Air Pulse stabilization circuit
- Operation Logging
- Residual quantity detection
- Multiple dispensing param channel
- High-Res dispensing pressure setting option

Applications

- Conformal Coating
- Underfill Dispensing
- Silicon-based Liquid Dispensing
- Tab Reinforcement
- Smartphone Cover Adhesive

Applications

- Jet-dispense AG paste on lead frame
- Jet-coat PCB to prevent moisture for automotive
- Jet-dispense UV resin
- Jet-bond various electronic parts
- Dispensing, dots, line, coating and more

MEASURING MASTER MPP-1 / MPP-3

Features

- Volumetric Dispensing with Outstanding Accuracy
- Consistent dispensing regardless of Viscosity change
- Superior Liquid cut-off suck back mechanism
- Excellent Constant Flow
- Various Liquid feeding methods

DUAL MPP-3

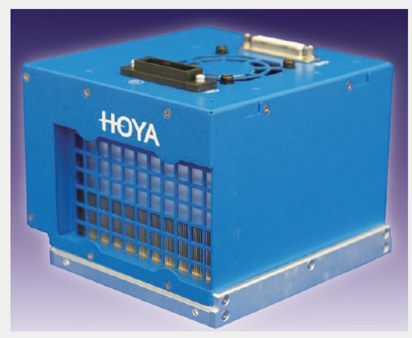
Features

- Configured for 2-part dispensing
- Excellent Constant Flow

UV LED Type

AREA

H-20AH4-FS1



HD240-V※-CN1A/-CN1A

LINE

EX120-V※-CN1A

H-4MLH84-1S12-SM1

SPOT

H-1VH

H-1VH4+HDL-Q1

UV Light Source Type

Execure 4000-D

UV Meter

HM-2. HD-365S. HD365

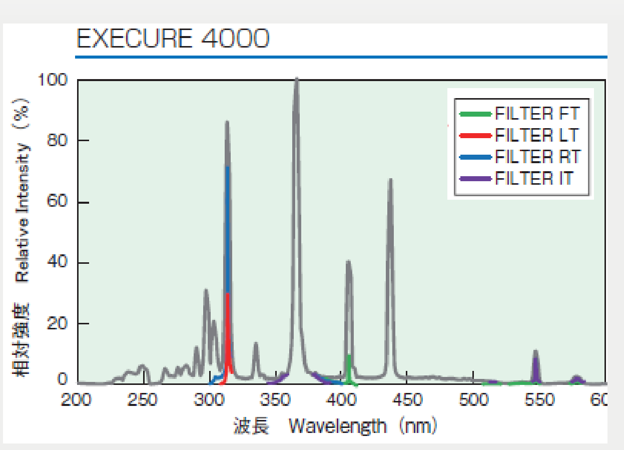
UV Light Technology

LED - Single Wavelength

395nm LED
405nm LED
385nm LED
375nm LED
UV ランプ
365nm LED
放射照度 （W/cm²）
波長 (nm)

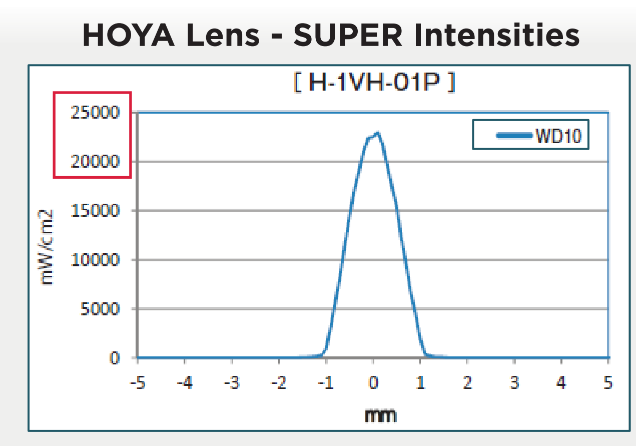
» High Irradiation Intensity
» Low Power Consumption
» Air Cooled Led Design
» Integration Friendly
» Long Chip Lifespan

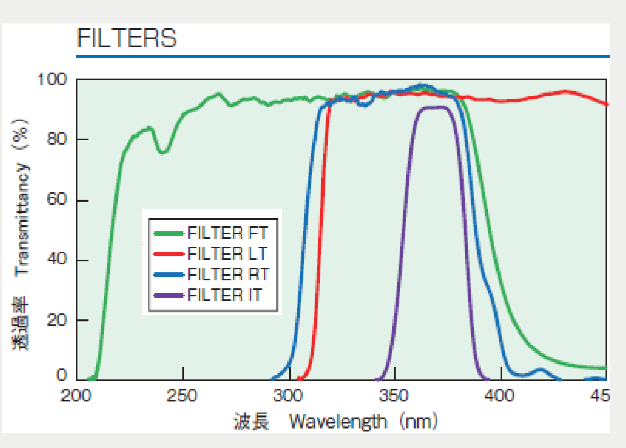
LIGHTSOURCE – Multi Wavelength



» Stable Irradiation Uniformity
» Ease of Maintenance
» Flexible Layout & Support
» Long Lamp Lifespan
» Interchangeable Filters

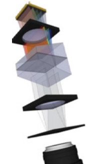
HOYA Lens - SUPER Intensities

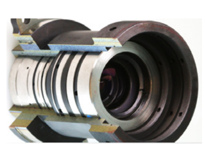




Adhesion/Bond Cure

HDD

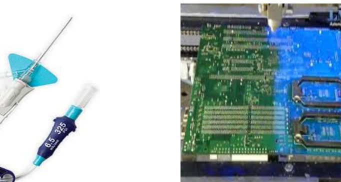

CCM


Optics

Micro Speaker

Medical

SEAL / COAT


PCB

Mobile

HOYA

SINGAPORE
Headquarter

More than 45 offices across
North America, Europe and Asia Pacific

- Manufacturing Plants -

Singapore • Malaysia • China • France • Poland

HEAD OFFICE
2304 Bedok Reservoir Road,
#05-00 Dou Yee Building,
Singapore 479223

Tel: (65) 6444 2678
Fax: (65) 6743 7172
Website: www.douyee.com
Email: s3_marketing@douyee.com.sg

Branches Contacts

S3_ GeneralCatalogue_EN_32pp_10.06.24_updated